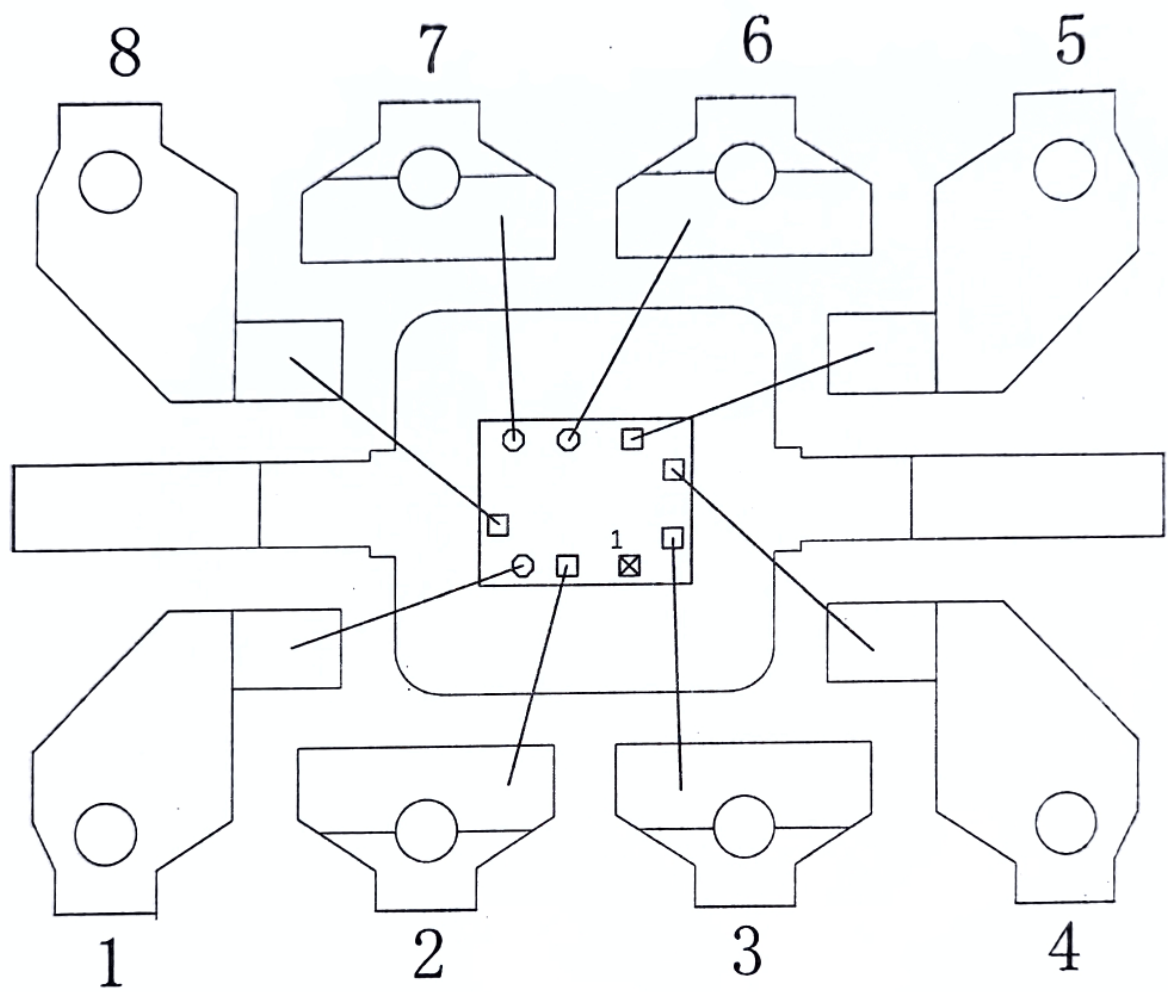

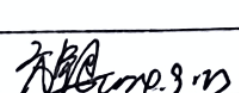
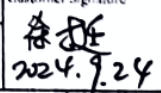
 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD				客户代码 Customer No.	008	线围号 Drawing No.	HY-PX-008-799 A	
焊线图纸 Bonding Diagram				产品名称 Product Type	HS0810		封装外型 PKG Type	SOP8L (12R)
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 N.O. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)		LF 焊盘尺寸 LF Pad Size
合金丝 Ag	20	8	9741	1087	896	优选(Preferred): EMG-600-2 备选(Optional): EME-G630AY		SOP8L-12R (60*60mil) (1524*1524μm ²)
客户图号 Customer drawing NO.								



封装传送方向(芯片): L/F Direction (D/A):	实物图: Chip photo:	特殊说明 Special Instructions:
椭圆孔 		DB注意: 芯片居中放置; WB注意: 数字为不打线pad点个数; 不管控三个八边形pad裂纹 HY-PX-008-799 A由HY-PX-008-301 A升级, 添加WB备注

说明 Instruction	贴片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size (μm ²)	最小焊盘尺寸 Min BPO (μm ²)	最小焊盘间距 Min BPP (μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	贴片线宽度 Street line (μm)	晶圆尺寸 Wafer size	是否过 Is with Bump	线厚厚度 Wire thickness
A芯: DIE A	导电胶 (conducivity) S210	HS5080	855*655(μm ²) 33.66*25.79(mil ²)	80*80	179	1.2	是 / Yes	80	6	否 / NO	300
B芯: DIE B											
C芯: DIE C											
编制 Prepared by			制图日期 Create Date	2024/9/23		生效日期 Effective Date			客户确认签字/盖章: Customer Signature		
研发审核 R&D Check			产品工程审核 PE Check			批准 Approved by			 2024.9.24		

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warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as leaving mistakes, which will produce incalculable loss. Thank you!